

B & D Enterprises
Main & Liberty
Russell, PA 16345
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TDA2581
TDA2581Q

CONTROL CIRCUIT FOR SMPS

The TDA2581 is a monolithic integrated circuit for controlling switched-mode power supplies (SMPS) which are provided with the drive for the horizontal deflection stage.

The circuit features the following:

- Voltage controlled horizontal oscillator.
- Phase detector.
- Duty factor control for the positive-going transient of the output signal.
- Duty factor increases from zero to its normal operation value.
- Adjustable maximum duty factor.
- Over-voltage and over-current protection with automatic re-start after switch-off.
- Counting circuit for permanent switch-off when n-times over-current or over-voltage is sensed.
- Protection for open-reference voltage.
- Protection for too low supply voltage.
- Protection against loop faults.
- Positive tracking of duty factor and feedback voltage when the feedback voltage is smaller than the reference voltage minus 1,5 V.

QUICK REFERENCE DATA

Supply voltage	V ₉₋₁₆	typ.	12	V
Supply current	I _g	typ.	15	mA
Input signals				
Horizontal drive pulse (peak-to-peak value)	V _{3-16(p-p)}	typ.	11	V
Flyback pulse (differentiated deflection current); peak-to-peak value	V _{2-16(p-p)}	typ.	5	V
External reference voltage	V ₁₀₋₁₆	typ.	6,7	V
Output signals				
Duty factor of output pulse	δ	>	0	%
		<	$98 \pm 0,6$	%
Output voltage at $I_o < 20$ mA (peak value)	V _{11-16M}	typ.	11,8	V
Output current (peak value)	I _{11M}	<	40	mA

PACKAGE OUTLINES

TDA2581: 16-lead DIL; plastic (SOT-38).

TDA2581Q: 16-lead QIL; plastic (SOT-58).

RATINGS

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Supply voltage	V ₉₋₁₆	max.	14 V
Voltage at pin 11	V ₁₁₋₁₆		0 to 14 V
Output current	I ₁₁	max.	40 mA
Total power dissipation	P _{tot}	max.	340 mW
Storage temperature	T _{stg}		-25 to +125 °C
Operating ambient temperature	T _{amb}		-25 to +80 °C

CHARACTERISTICSV₉₋₁₆ = 12 V; V₁₀₋₁₆ = 6,7 V; T_{amb} = 25 °C; measured in the circuit on page 2

Supply voltage range	V ₉₋₁₆	typ.	12 V 10 to 14 V
Protection voltage too low supply voltage	V ₉₋₁₆	typ.	9,4 V 8,6 to 9,9 V
Supply current at $\delta = 50\%$	I ₉	typ.	15 mA
Supply current during protection	I ₉	typ.	15 mA
Minimum required supply current	I ₉	<	18,5 mA*
Power consumption	P	typ.	180 mW
Required input signals			
Reference voltage	V ₁₀₋₁₆	typ.	6,7 V 5,6 to 7,5 V**
High reference voltage protection: threshold voltage	V ₁₀₋₁₆	typ.	8,4 V 7,9 to 8,9 V
Feedback input impedance at pin 8	Z ₈₋₁₆	typ.	200 kΩ
Horizontal drive pulse (square-wave or differentiated; negative transient is reference) peak-to-peak value	V _{3-16(p-p)}	typ.	11 V 5 to 12 V
Flyback pulse or differential deflection current	V ₂₋₁₆		1 to 5 V
Over-current protection: threshold voltage	-V ₆₋₁₆	typ.	640 mV 690 to 695 mV▲
	+V ₆₋₁₆	typ.	680 mV 640 to 735 mV▲
Over-voltage protection: threshold voltage	V ₇₋₁₆	typ.	V ₁₀₋₁₆ -60 mV V ₁₀₋₁₆ -130 to V ₁₀₋₁₆ -0 mV

* This value refers to the minimum required supply current that will start all devices under the following conditions: V₉₋₁₆ = 10 V; V₁₀₋₁₆ = 6,8 V; $\delta = 50\%$.

** Voltage obtained via an external reference diode. Specified voltages do not refer to the nominal voltages of reference diodes.

▲ This spread is inclusive temperature rise of the IC due to warming up. For other ambient temperatures the values must be corrected by using a temperature coefficient of typical -1,85 mV/°C.

CHARACTERISTICS (continued)

Remote control voltage; switch off
switch on

V₄₋₁₆ > 5,8 V*
V₄₋₁₆ < 4,5 V*

Delivered output signals

Horizontal drive pulse (loaded with a resistor
of 560 Ω to +12 V)
peak-to-peak value

V_{11-16(p-p)} > 11,6 V
I_{11M} < 40 mA

Output current; peak value

V_{CESat} typ. 200 mV
< 400 mV

Saturation voltage of output transistor
at I₁₁ = 20 mA

V_{CESat} < 525 mV

at I₁₁ = 40 mA

> 0 %
< 98 ± 0,6 %

Duty factor of output pulse**

I₄ typ. 120 μA
I₅ typ. 130 μA

Charge current for capacitor on pin 4

I₁₀ typ. 1 mA
0,6 to 1,45 mA

Charge current for capacitor on pin 5

Supply current for reference

Oscillator

Temperature coefficient

typ. -300 ppm/°C
< -400 ppm/°C

Relative frequency deviation for V₁₀₋₁₆
changing from 6 to 7 V

typ. -1,5 %
≤ -2 %

Oscillator frequency spread (with fixed
external components)

≤ ±3 %
typ. 4,5 kHz/V▲

Frequency control sensitivity at pin 15

Phase control loop

Loop gain of APC-system (automatic phase control)

typ. 5 kHz/μs

Catching range

typ. ±1,5 kHz

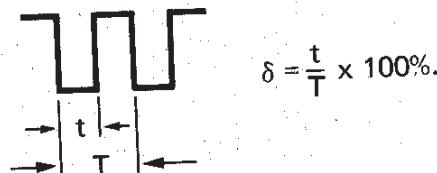
Phase relation between negative transient of
sync pulse and middle of flyback

t typ. 1 μs
Δt ≤ ±0,4 μs

Tolerance of phase relation

* See pin 4 on pages 7 and 8.

** The duty factor is specified as follows:



The maximum duty factor value can be set to a desired value (see application information pin 12
page 9).

▲ For component values see circuit diagram on page 2.

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PINNING

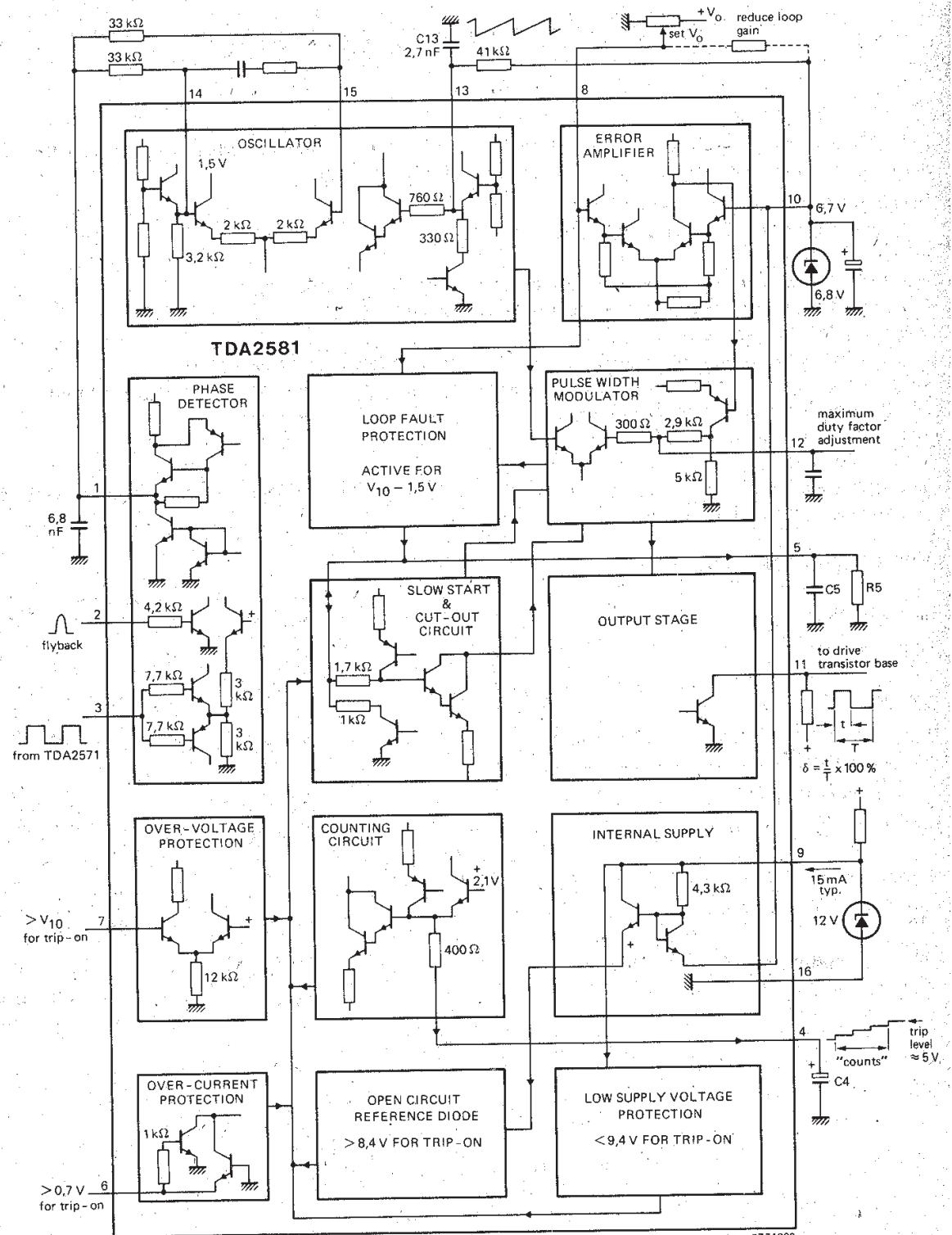
1. Phase detector output
2. Flyback pulse position input
3. Reference frequency input
4. Re-start count capacitor/remote control input
5. Slow start and transfer characteristic for low feedback voltages
6. Over-current protection input
7. Over-voltage protection input
8. Feedback voltage input
9. Positive supply
10. Reference input
11. Output
12. Maximum duty factor adjustment/smoothing
13. Oscillator timing network
14. Reactance stage reference voltage
15. Reactance stage input
16. Negative supply (ground)

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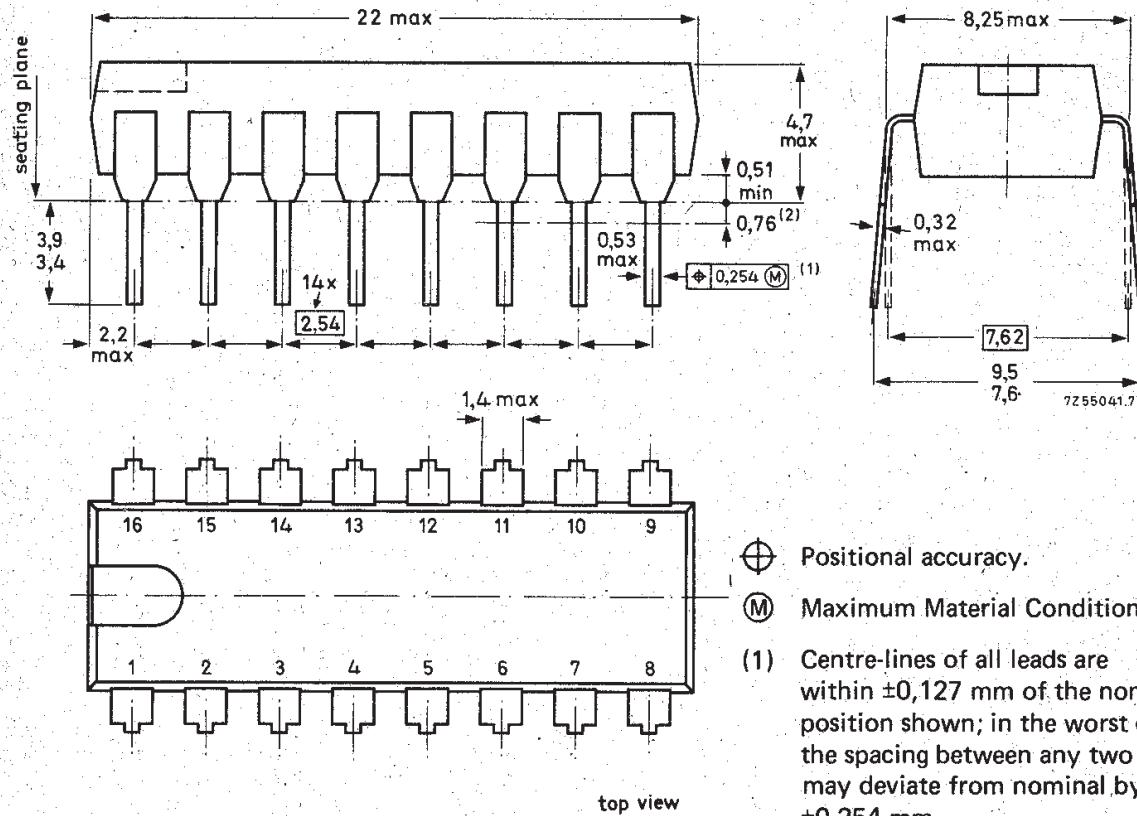
BLOCK DIAGRAM



Note: trip levels are nominal values.

PACKAGE OUTLINES

16-LEAD DUAL IN-LINE; PLASTIC (SOT-38)



Dimensions in mm

SOLDERING

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1. By hand

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C it must not be in contact for more than 10 seconds; if between 300 °C and 400 °C, for not more than 5 seconds.

2. By dip or wave

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

3. Repairing soldered joints

The same precautions and limits apply as in (1) above.

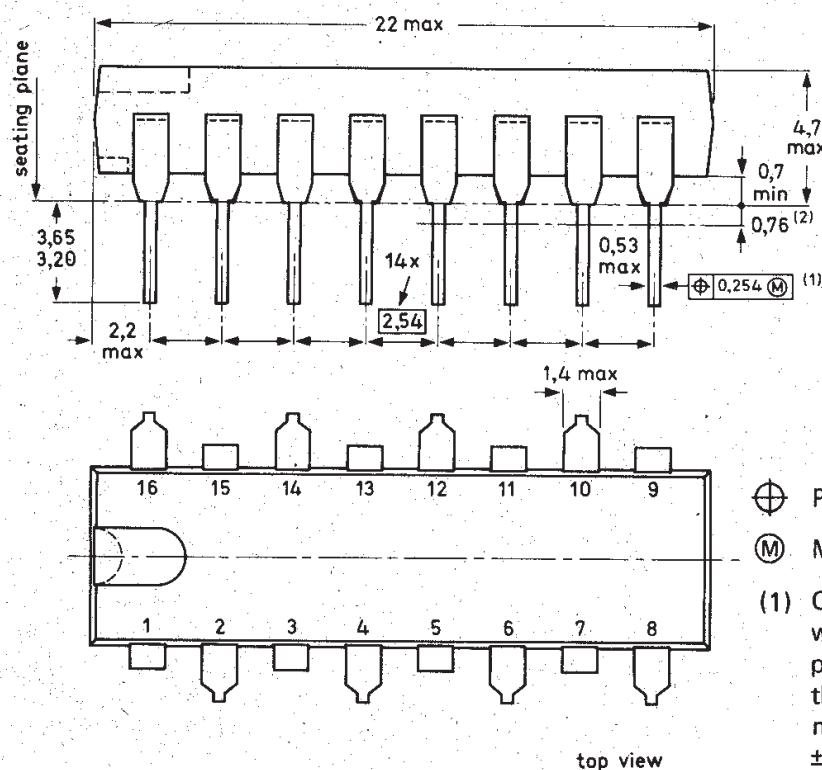
(Positional accuracy.

(Maximum Material Condition.

(1) Centre-lines of all leads are within ± 0.127 mm of the nominal position shown; in the worst case, the spacing between any two leads may deviate from nominal by ± 0.254 mm.

(2) Lead spacing tolerances apply from seating plane to the line indicated.

16-LEAD QUADRUPLE IN-LINE; PLASTIC (SOT-58)



Dimensions in mm

Positional accuracy.

Maximum Material Condition.

- (1) Centre-lines of all leads are within ± 0.127 mm of the nominal position shown; in the worst case, the spacing between any two leads may deviate from nominal by ± 0.254 mm.
- (2) Lead spacing tolerances apply from seating plane to the line indicated.

SOLDERING

1. By hand

Apply the soldering iron below the seating plane (or not more than 2 mm above it). If its temperature is below 300 °C it must not be in contact for more than 10 seconds; if between 300 °C and 400 °C, for not more than 5 seconds.

2. By dip or wave

The maximum permissible temperature of the solder is 260 °C; this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified storage maximum. If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

3. Repairing soldered joints

The same precautions and limits apply as in (1) above.